5-146278-6 ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 5-146278-6

PCB Mount Header, Vertical, Board-to-Board, 6 Position, 2.54 mm [.

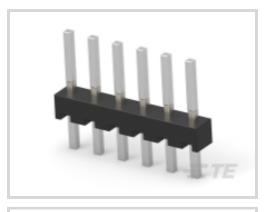
1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal,

AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles

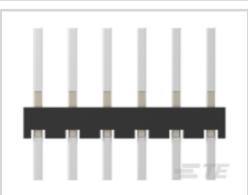








-65 – 105 °C[-85 – 221 °F]



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 6
Number of Rows: 1

Features

Electrical Characteristics

Electrical Characteristics	
Operating Voltage	30 VAC
Dimensions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Packaging Features	
Packaging Quantity	240
Packaging Method	Carton
Industry Standards	
Compatible With Approved Standards Products	UL E28476, CSA LR7189
UL Flammability Rating	UL 94V-0
Usage Conditions	
Housing Temperature Rating	High

Operating Temperature Range



Primary Product Color Black Operation/Application Solder Process Feature Roard Standoff Circuit Application Signal Termination Features Termination Post & Tail Length 3.05 mm/(12 in) Square Termination Post & Tail Dimension .64 mm/(025 in) Termination Method to PCB Through Hole - Solder Contact Underplating Material Nickel Contact Underplating Material Nickel Contact Mating Area Pating Material Thickness 2.54 – 5.09 µm/(100 – 200 µin) Mating Square Post Dimension .64 mm/(10% in) Contact Shape & Form Square Contact Base Material Phosphor Bronze PCB Contact Termination Area Plating Material Tin Contact Uppe Pin Contact Uppe Pin Contact Current Rating (Max) 3.A Housing Material LCP GF (Liquid Crystal Polymer), LCP (Tiquid Crystal Polymer), LCP (Tiquid Crystal Polymer) Configuration Features Configuration Features Connector Contact Load Condition Fully Loaded Board to Board Configuration Parallel	Connector Profile	Standard
Solder Process Feature Circuit Application Signal Termination Features Termination Features Termination Post & Tail Length Square Termination Post & Tail Dimension Ad mm[.025 in] Termination Method to PCB Through Hole - Solder Contact Features Contact Underplating Material Contact Mating Area Plating Material Thickness Ad mm[.025 in] Mating Square Post Dimension Ad mm[.025 in] 100 - 200 µin Contact Shape & Form Square Contact Hase Material Phosphor Bronze Contact Hase Material PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Type Pin Contact Current Rating (Max) AA Housing Features Housing Material LCP-GF (Liquid Crystal Polymer), LCP (Tiquid Crystal Polymer), LCP (Tiquid Crystal Polymer) Contact Department Features Connector Contact Load Condition Parallel PCB Mount Orientation Vertical Number of Positions A Uniform of Rows Number of Rows 1 Product Type Features	Primary Product Color	Black
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Termination Method to PCB Contact Features Contact Underplating Material Contact Mating Area Plating Material Thickness Mating Square Post Dimension Mating Square Material Material Material Material Material Material Material Material Material Max Material Max Material Max Material Max Material Max Material Max Material Mat	Termination Post & Tail Length	3.05 mm[.12 in]
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Contact Mating Area Plating Material Thickness 2.54 – 5.08 µm[100 – 200 µin] Mating Square Post Dimension 6.44 mm[.025 in] 100 – 200 µin Contact Shape & Form Square Contact Base Material Phosphor Bronze PCB Contact Termination Area Plating Material Tin Contact Mating Area Plating Material Tin Contact Type Pin Contact Current Rating (Max) 3 A Housing Features Housing Material LCP GF (Liquid Crystal Polymer), LCP (Liquid Crystal Polymer) Centerline (Pitch) 2.54 mm[.1 in] Configuration Features Connector Contact Load Condition Fully Loaded Board-to-Board Configuration PCB Mount Orientation Vertical Number of Positions 6 Number of Rows 1	Contact Features	
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Contact Type Pin Contact Current Rating (Max) 3 A Housing Features Housing Material LCP-GF (Liquid Crystal Polymer), LCP (Liquid Crystal Polymer) Centerline (Pitch) 2.54 mm[.1 in] Configuration Features Connector Contact Load Condition Fully Loaded Board-to-Board Configuration Parallel PCB Mount Orientation Vertical Number of Positions 6 Number of Rows 1 Product Type Features	PCB Contact Termination Area Plating Material	Tin
Contact Current Rating (Max) Housing Features Housing Material Centerline (Pitch) Configuration Features Connector Contact Load Condition Board-to-Board Configuration PCB Mount Orientation Number of Positions Number of Rows Product Type Features 3 A LCP-GF (Liquid Crystal Polymer), LCP (Liquid Crystal Polymer) 2.54 mm[.1 in] Fully Loaded Purallel Vertical Number of Positions 6 Number of Rows 1	Contact Mating Area Plating Material	Tin
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Configuration Features Connector Contact Load Condition Fully Loaded Board-to-Board Configuration Parallel PCB Mount Orientation Vertical Number of Positions 6 Number of Rows 1 Product Type Features	Housing Material	·
Connector Contact Load Condition Board-to-Board Configuration PCB Mount Orientation Number of Positions Number of Rows 1 Product Type Features	Centerline (Pitch)	2.54 mm[.1 in]
Board-to-Board Configuration Parallel PCB Mount Orientation Vertical Number of Positions 6 Number of Rows 1 Product Type Features	Configuration Features	
PCB Mount Orientation Number of Positions 6 Number of Rows 1 Product Type Features	Connector Contact Load Condition	Fully Loaded
Number of Positions 6 Number of Rows 1 Product Type Features 4	Board-to-Board Configuration	Parallel
Number of Rows 1 Product Type Features	PCB Mount Orientation	Vertical
Product Type Features	Number of Positions	6
	Number of Rows	1
PCB Connector Assembly Type PCB Mount Header	Product Type Features	
	PCB Connector Assembly Type	PCB Mount Header



Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Mechanical Attachment	
PCB Mount Retention	Without

PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	Without

Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Also in the Series | AMPMODU Headers



Automotive Headers(3)



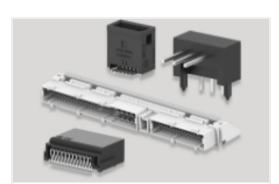
Board-to-Board Headers & Receptacles(1571)



Connector Contacts(52)



Connector Hardware(1)



PCB Headers & Receptacles(1618)



Wire-to-Board Connector Assemblies & Housings(5)



Wire-to-Board Headers & Receptacles (116)

Customers Also Bought



TE Part #3-647166-5
5P MTA100 HDR ASSY,SM,FL,LF



TE Part #2-1827875-3

DYNAMIC 1200D HDR ASSY V 6P Y

BLACK GOLD



TE Part #3-2176070-2 3521 200R 1% 2W



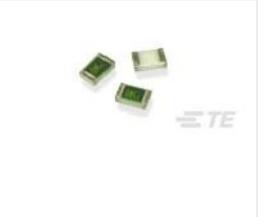
TE Part #1-1123723-7
3.96 EP HDR ASSY 7P(NATURAL)



TE Part #1-1676481-7 CPF 0603 24R 0.1% 25PPM 1K RL



TE Part #1571610-2 Sealed R/A Tact switch, Sealed



TE Part #9-2176091-6 RP 2A 0.25W 590R 0.1% 25PPM 1K RL



TE Part #3-2176338-7 CRGCQ 0402 1M0 5%







TE Part #5052912021 RNF-100-1/16-4-STK TE Part #1-1969582-0 ASSY, HDR, VERT, NO-BOSS, DUAL ROW,EP2.5

Documents

Product Drawings

06 MODII HDR SRST B/A .100CL

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-146278-6_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-146278-6_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-146278-6_E.3d_stp.zip

English

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